



LMP ALLOY - This ternary soldering alloy is dedicated for soldering in electronic, telecom and spatial applications.

Sn50PbCd18 is a low melting point alloy corresponding to NFC90550 normalisation under reference B. Sn50PbCd18.

Chemical Characteristics

Amount of Tin:	50% \pm 0.6%
Amount of Lead:	32% +/- 0.4%
Amount of Cadmium:	18 % +/- 0.2%

Chart of maximum impurities, example:

Cu	Ag	Sb	Bi
0.05%	0.005%	0.05%	0.01%

Fe	Zn	Al	As	Div
0.02%	0.001%	0.001%	0.01%	0.05%

Physical Characteristics, standard:

ALLOY Sn50Pb32Cd18	
Melting point	145°C (Eutectic)
Specific weight	8.5 g/cm ³
Working temperature	270 – 320 °C

Packaging

Standard: Wire
Others: Sticks, Bars, Ingots
Labelling: Cartons/containers labels show manufactured lot N° and Alloy

Storage

In original packaging at ambient conditions.